



☐ Drafts
☒ Pending
☒ Active
 L1: (183275) ROM or (read adj only adj memory)
 L2: (4946) 1 and implant\$3 and oxid\$4
 L3: (582) 2 and (oxid\$4 near (substrate or sidewall\$1))
 L4: (282) 3 and buried
 L5: (74) 4 and (thermal adj (oxidizing or oxide))
 L6: (64) 5 and insulat\$3
 L7: (64) 6 and (conduct\$3 or polysilicon)
 L8: (46) 7 and (memory.clm. or ROM.clm. or (read adj2 memory).clm.)
 L9: (37) 7 and (oxide.clm. or oxidizing.clm.)
 L10: (37) 7 and (oxide.clm. or oxidizing.clm. or oxidation.clm. or oxidized.c
 L11: (23) 10 and (oxid\$4 near sidewall\$1)
 L12: (0) 10 and ((oxidizing or oxidation or oxidized) near sidewall\$1)
☐ Failed
☒ Saved
 (136) ((substrate adj jig) or (jig adj substrate))
 (49) ((substrate adj jig) or (jig adj substrate)) and (fix\$3 or dicing or gr
 (68) (((substrate adj jig) or (jig adj substrate)) and (fix\$3 or dicing or gr
 (23) (((substrate adj jig) or (jig adj substrate)) and (fix\$3 or dicing or g
 (12) (((substrate adj jig) or (jig adj substrate)) and (flat\$3 or warp\$3)) a
 (3960) jig.clm.
 (495) jig.clm. and substrate
 (17) (jig.clm. and substrate) and (((back adj grind) or dicing or (side adj bo
 (1) (jig.clm. and substrate) and ((back adj grind) with jig)

☒ DBs: ☒ USPAT:US:PGPU6 ☒ Purvis

Default operator: ☒ Highlight all hit terms in body

	V	I	Document ID	Issue Date	Pages	Title	Current OR	Current XRef	Retrieval C	Inventor	S	C	P	3	Tr
3			US 6509599 B1	20030121	25	Trench capacitor with insulation collar and method	257/301	257/304;		Wurster, Kai et al.					US
4			US 6500768 B1	20021231	12	Method for selective removal of ONO layer	438/738	257/E21.651; 438/723; 438/724;		Shields, Jeffrey A. et al.					US
5			US 6433382 B1	20000613	27	Split-gate vertically oriented EEPROM device and p	257/315	257/329; 257/E27.123;		Ostrowski, Marius et al.					US
6			US 6417040 B2	20020719	33	Method for forming memory array having a digit line bu	438/238	257/E21.648; 257/E27.089;		Noble, Wendell					US
7			US 6410391 B1	20020625	19	Method for producing an EEPROM memory cell with a tr	438/259	257/E21.645; 257/E21.653;		Selsacher, Rudolf					US
8			US 6391149 B1	20010701	26	Method of fabricating nonvolatile memory device	438/257	257/E21.68; 257/E27.133;		Choi, Woong-Iin et al.					US
9			US 6200073 B1	20010313	31	Production method for a trench capacitor with an ins	438/306	257/E21.651; 438/242;		Schrems, Martin et al.					US
10			US 6191550 B1	20010101	11	Dense SOI programmable logic array structure	438/149	257/E21.689; 257/E21.733;		Noble, Wendell F.					US
11			US 6046477 A	20000404	9	Dense SOI programmable logic array structure	257/347	257/350; 257/354;		Noble, Wendell F.					US